

### Applications

- Cellular phones
- Portable devices
- Digital cameras
- Power supplies

### Features

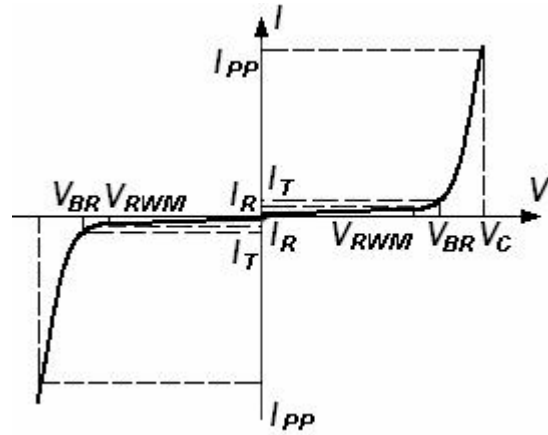
- Small Body Outline Dimensions
- Low Body Height
- Peak Power up to 200 Watts @ 8 x 20  $\mu$ s Pulse
- Low Leakage current
- Response Time is Typically < 1 ns
- ESD Rating of Class 3 (> 16 kV) per Human Body Model
- IEC61000-4-2 Level 4 ESD Protection
- IEC61000-4-4 Level 4 EFT Protection

### Absolute Ratings ( $T_{amb}=25^{\circ}C$ )

Symbol	Parameter	Value	Units	
$P_{PP}$	Peak Pulse Power ( $t_p = 8/20 \mu s$ )	200	W	
$T_L$	Maximum lead temperature for soldering during 10s	260	$^{\circ}C$	
$T_{stg}$	Storage Temperature Range	-55 to +155	$^{\circ}C$	
$T_{op}$	Operating Temperature Range	-40 to +125	$^{\circ}C$	
$T_j$	Maximum junction temperature	150	$^{\circ}C$	
	IEC61000-4-2 (ESD)	air discharge contact discharge	$\pm 15$ $\pm 8$	KV
	IEC61000-4-4 (EFT)		40	A
	ESD Voltage	Per Human Body Model	16	KV

**Electrical Parameter**

Symbol	Parameter
$I_{PP}$	Maximum Reverse Peak Pulse Current
$V_C$	Clamping Voltage @ $I_{PP}$
$V_{RWM}$	Working Peak Reverse Voltage
$I_R$	Maximum Reverse Leakage Current @ $V_{RWM}$
$I_T$	Test Current
$V_{BR}$	Breakdown Voltage @ $I_T$



**Electrical Characteristics** Ratings at 25°C ambient temperature unless otherwise specified. VF = 0.9V at IF = 10mA

Device	Device Marking	$V_{RWM}$ (V)	$I_R$ (uA) @ $V_{RWM}$	$V_{BR}$ (V) @ $I_T$ (Note 1)		$I_T$ (mA)	$V_C$ (V) @ $I_{PP}=5 A^*$	$V_C$ (V) @ Max $I_{PP}^*$	$I_{PP}$ (A)*	$P_{PK}$ (W)*	C (pF)
		Max	Max	Min	Max		Typ	Max			
ESD05V52D-C	5C	5.0	1.0	5.6	7.8	1.0	11.6	18.6	9.4	174	25

1.  $V_{BR}$  is measured with a pulse test current  $I_T$  at an ambient temperature of 25°C.

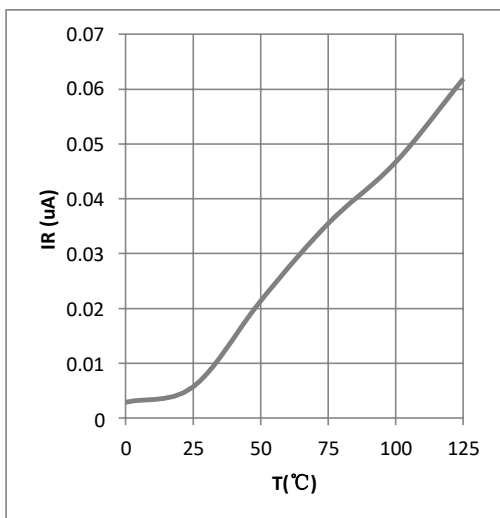


Fig 1. Reverse character

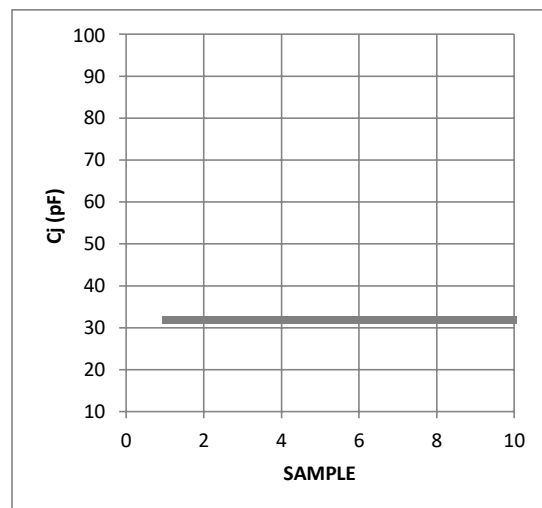
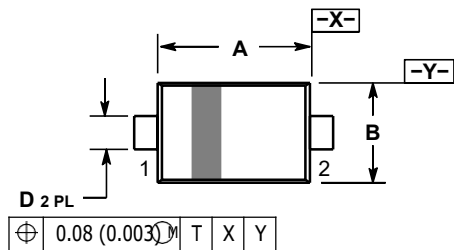


Fig 2. Capacitance character

## Package Outline Dimensions

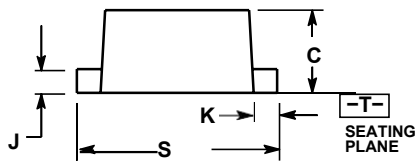
### SOD-523



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	1.10	1.20	1.30	0.043	0.047	0.051
B	0.70	0.80	0.90	0.028	0.032	0.035
C	0.50	0.60	0.70	0.020	0.024	0.028
D	0.25	0.30	0.35	0.010	0.012	0.014
J	0.07	0.14	0.20	0.0028	0.0055	0.0079
K	0.15	0.20	0.25	0.006	0.008	0.010
S	1.50	1.60	1.70	0.059	0.063	0.067



### SOLDERING FOOTPRINT\*

